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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/085,757	02/27/2002	Bo Soon Chang	CYPR-PM01008	8405

7590 07/02/2004

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EXAMINER
JARRETT, RYAN A

ART UNIT	PAPER NUMBER
2125	

DATE MAILED: 07/02/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	10/085,757	CHANG, BO SOON
Examiner	Art Unit	
Ryan A. Jarrett	2125	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 10 May 2004.
 2a) This action is FINAL. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-49 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 1-49 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on 10 May 2004 is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
 Paper No(s)/Mail Date _____

4) Interview Summary (PTO-413)
 Paper No(s)/Mail Date. _____
 5) Notice of Informal Patent Application (PTO-152)
 6) Other: _____

DETAILED ACTION

Response to Arguments

1. Applicant's arguments filed 5/10/04 have been fully considered but they are not persuasive. Applicant argues that the relied upon prior art does not teach or suggest that the die-strips are processed on an in-line basis. However, Jin discloses that the cleaning equipment and fabricating equipment are arranged in an "in-line" fashion, e.g., such that the PCB's can be introduced into the fabrication immediately after finished in the cleaning equipment (e.g. col. 1 lines 7-19, Fig. 1, Fig. 2). Thus, the PCB's are not delayed in a batch fashion.

Claim Rejections - 35 USC § 103

2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

3. Claims 1-4, 6, 8-16, 18, 20, 21, 23, 24, 26, 27, and 29-36 are rejected under 35 U.S.C. 103(a) as being unpatentable over Admitted Prior Art in view of Jin et al. U.S. Patent No. 6,392,286 (Admission-Jin). Admission discloses an IC back-end manufacturing assembly comprising: a front-of-line portion comprising a plurality of sub-stations for operating on a plurality of die-strips in an in-line basis commencing with an in-line die attach sub-station and ending with a in-line plasma sub-station; and an

end-of-line portion receiving processed die-strips from said front-of-line portion in an in-line fashion and comprising a plurality of sub-stations for operating on said processed die-strips in an in-line basis commencing with an in line mold sub-station and ending with a sort sub-station; further comprising: an in-line test portion receiving die-strip components output from said in-line sort sub-station and for testing said die-strip components; and a finish portion coupled to said in-line test portion and comprising a plurality of sub-stations operating on tested die-strip components output from said in-line test portion and commencing with a marking sub-station and ending with a tape and reel sub-station; wherein one of said plurality of sub-stations of said front-of-line portion further comprises another in-line plasma sub-station; wherein one of said plurality of sub-stations of said front-of-line portion is an in-line snap cure substation; wherein one of said plurality of sub-stations of said front-of-line portion is an in-line bond substation; wherein said plurality of sub stations of said end-of-line portion further comprise: an in-line post mold cure sub-station coupled to said in-line mold sub-station; an in-line solder ball attachment sub-station; and an in-line sawing sub-station coupled to said sort sub-station; wherein said plurality of substations of said finish portion further comprise a final visual inspection sub-station coupled between said marking sub-station and said tape and reel sub-station (Fig. 1, pg. 3 line 4 – pg. 7 line 20);

an apparatus for automatically performing back-end fabrication of an IC device comprising: (a) a die attach module adapted to attach a plurality of IC die to a substrate under computer control; (b) a bonding module adapted to bond wires to both the substrate and the attached die under computer control; (c) a molding module adapted to

encapsulate bonded die and substrate with a mold material under computer control; (d) a singulation module adapted to separate encapsulated, bonded die and substrate under computer control into separated die; (e) a testing module adapted to test the separated die under computer control; and (f) a plurality of transporters adapted to transport: (i) the substrate and the attached die from the die attach module to the bonding module; (ii) the bonded die and substrate from the bonding module to the molding module; (iii) the encapsulated, bonded die and substrate from the molding module to the singulation module; and (iv) the separated die from the singulation module to the testing module; further comprising a marking module adapted to mark the tested die under computer control; further comprising a packaging module adapted to package the tested die under computer control to produce packaged die; wherein the packaging module comprises a tape and reel module; further comprising a snap curing module adapted to snap cure an adhesive adapted to attach the plurality of die to the substrate; further comprising an in-line plasma cleaning module adapted to plasma clean the substrate and attached die; further comprising an in-line plasma cleaning module adapted to plasma clean the bonded substrate and die; wherein the singulation module comprises a sawing module; further comprising a sawing module adapted to saw wafers under computer control to provide said separated die (Fig. 1, pg. 3 line 4 – pg. 7 line 20).

In the Admission, the transporters consist of human operators that transfer the workpieces between the various assembly line modules. There is no disclosure in the Admission of any type of automatic transfer device, such as a conveyor, that transfers

the workpieces between the assembly line modules. However, Jin discloses a semiconductor chip packaging system comprising a conveyor that automatically transports semiconductor die between various assembly line modules in an in-line fashion, the modules comprising sawing equipment, die attach equipment, cleaning tools, wire bonding equipment, molding equipment, and singulation equipment. Each of the assembly equipments includes a loading part and an unloading part. Jin also discloses that the substrate holding the die comprises an n-by-m matrix array ball grid array (BGA) substrate and wherein n and m each independently being an integer of at least 2 (e.g. Figs. 1-4, col. 1 lines 7-20, col. 3 lines 55 – col. 4 line 6, col. 4 lines 26-31, col. 5 lines 19-54, col. 9 lines 10-35, col. 9 line 61 – col. 10 line 67, col. 11 line 25 – col. 12 line 14). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the Admission with Jin since Jin teaches that an automatic conveyor can speed up processing and eliminate the need for an extra operator (e.g. col. 4 lines 26-31).

Additionally, Jin discloses that the processing is done on an in-line basis, i.e., a next one of the processed die strips or substrate enters a module as soon as a previous one of the processed die strips or substrates clears the module (e.g., col. 1 lines 7-20, col. 4 lines 13-25, col. 5 lines 19-30, col. 11 lines 62-67).

4. Claims 5, 7, 17, 19, 22, 25, 28, and 37-49 are rejected under 35 U.S.C. 103(a) as being unpatentable over Admission-Jin as applied to claims 4, 6, 12, 18, 21, 24, and 27 above, and further in view of Farnsworth et al. Admission-Jin discloses multiple manual

visual inspection stations located on the assembly line (e.g., Fig. 1 of Admission). Admission-Jin does not disclose the use of camera systems for performing automated die-strip inspections at the die attach, bond, mold, solder ball attachment, or sorting substations. However, Farnsworth et al. discloses a method for packaging electronic components. The process sequence comprises die attach, bond, mold, solder ball attach, test, marking, and packaging modules (e.g. Fig. 9). Farnsworth et al. also discloses a camera/automated machine vision system adapted to inspect the encapsulated, marked, bonded die and substrate (e.g. col. 4 line 59 – col. 5 line 11, col. 6 line 35-55, col. 9 line 60 – col. 11 line 6). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify Admission-Jin with Farnsworth et al. since Farnsworth et al. teaches that an automatic machine vision system can be used in a back-end semiconductor assembly line to eliminate the precise mechanical alignment of workpieces that was necessary in the prior art. Accordingly, accurate workpiece alignment and material disposition can be reliably obtained (e.g. col. 4 line 59 – col. 5 line 4).

Conclusion

5. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not

mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ryan A. Jarrett whose telephone number is (703) 308-4739. The examiner can normally be reached on 10:00-6:30 M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Leo Picard can be reached on (703) 308-0538. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Ryan A. Jarrett
Examiner
Art Unit 2125

6/26/04

Albert W. Paladini C-28-C
ALBERT W. PALADINI
PRIMARY EXAMINER